

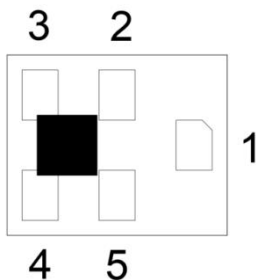
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

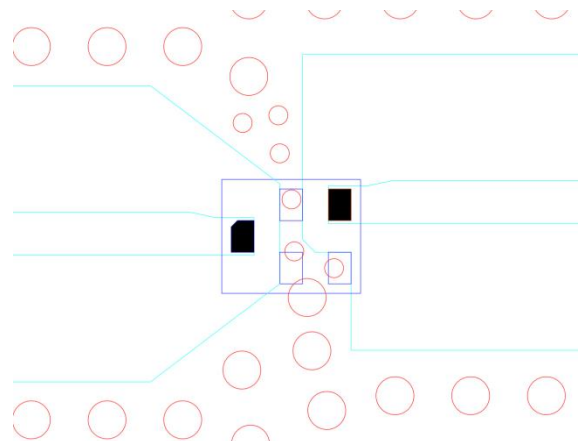
NO.	Parameter	Frequency (MHz)	Min.	Max.
1	Insertion Loss (dB)	2300~2690		1.8
2	Return Loss (dB)	2300~2690		10
3	Attenuation (dB)	4600~5380	25	
		6900~8000	20	
4	In/Output Impedance (Ω)	50		

Construction



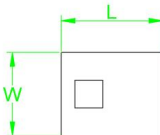

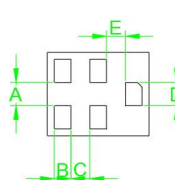
PIN	Connection
1	Input port
2	GND
3	GND
4	Output port
5	GND

Mounting Considerations

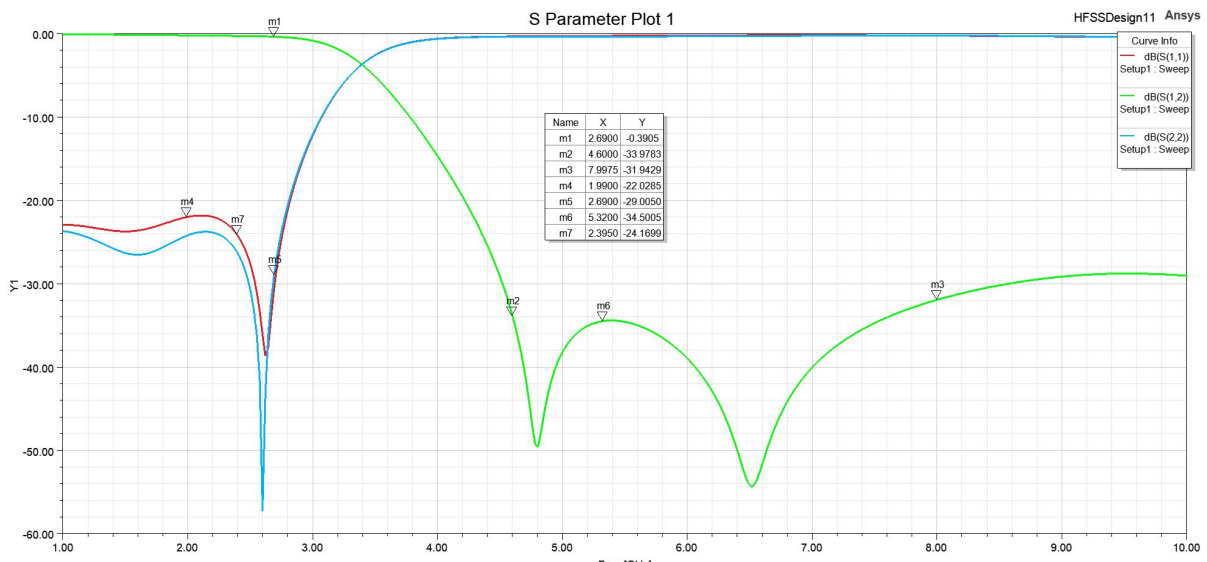


Unit: mm
 Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

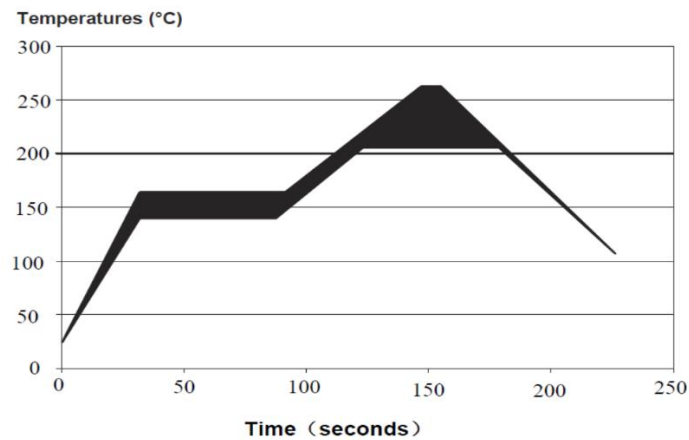
Dimensions

Figure	Symbol	Dimension (mm)
<div style="display: flex; justify-content: space-around; align-items: center;"> <div style="text-align: center;"> <p>TOP VIVE</p>  </div> <div style="text-align: center;"> <p>SIDE VIVE</p>  </div> <div style="text-align: center;"> <p>BOTTOM VIVE</p>  </div> </div>	L	1.10±0.10
	W	0.90±0.10
	T	0.50±0.10
	A	0.25±0.05
	B	0.18±0.05
	C	0.21±0.05
	D	0.25±0.05
E	0.21±0.05	

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.